ON Semiconductor

UPDATE CHANGE NOTIFICATION #20324-D

Generic Copy

Issue Date: 09-Sep-2014

TITLE: Update Change Notification to FPCN20324-D for Assembly and Test site transfer from Kanto Sanyo Semiconductors Co., Ltd to ON Semiconductor SSMP Philippines Corporation (Group 01-D)

PROPOSED FIRST SHIP DATE: 24-Oct-2014 or earlier upon approval due to shortage of product

AFFECTED CHANGE CATEGORY(S): Assembly and Test site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or
<toshiitsu.igarashi@onsemi.com><takeshi2.hoshino@onsemi.com> <shinya.okada@onsemi.com>
<ikuo.saeki@onsemi.com><Toshimitsu.Namiki@onsemi.com><naoki.koyama@onsemi.com>
<takehito.tsukui@onsemi.com> <keiji.ueda@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or <jun.hasunuma@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or
<Takashi.Naruse@onsemi.com><Satoru.Fujinuma@onsemi.com>

NOTIFICATION TYPE:
Update Change Notification to FPCN.

DESCRIPTION AND PURPOSE:

FPCN20324-D announced on 23-Jul-2014 that the products and the equipments will be transferred from Hanyu plant of Kanto Sanyo Semiconductors Co., Ltd to ON Semiconductor SSMP Philippines Corporation because Hanyu plant of Kanto Sanyo Semiconductors Co., Ltd was closed at the end of June, 2014.

FPCN20324-DA also showed the reliability result of 168hr because reliability test was still in process at that time.

This update notification is to announce that the reliability evaluation result of 1000hr for the transferred products was completed and has no problem.

The materials and package outline of these products remain identical. Qualification tests are designed to show that the reliability of transferred devices continue to meet or exceed ON Semiconductor standards.

UPDATE CHANGE NOTIFICATION #20324-D

RELIABILITY DATA SUMMARY:

Package name : VCT16

Test Items	Test Condition	Test Time	Results
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended	1000hrs	Pass
Temperature Humidity Storage *	Ta=85degC,RH=85%	1000hrs	Pass
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	Pass
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	100hrs	Pass
High Temperature Storage	Ta=150degC	1000hrs	Pass
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times	Pass
Solderability	245degC,3s(with Flux) Soldering area,95% over(Sn-3.0Ag-0.5Cu)	1time	Pass

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification. (Except for Solderability)

Package name : VCT20

Test Items	Test Condition	Test Time	Results
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended	1000hrs	Pass
Temperature Humidity Storage *	Ta=85degC,RH=85%	1000hrs	Pass
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	Pass
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	100hrs	Pass
High Temperature Storage	Ta=150degC	1000hrs	Pass
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times	Pass
Solderability	245degC,3s(with Flux) Soldering area,95% over(Sn-3.0Ag-0.5Cu)	1time	Pass

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification. (Except for Solderability)

Package name : VCT24

Test Items	Test Condition	Test Time	Results
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended	1000hrs	Pass
Temperature Humidity Storage *	Ta=85degC,RH=85%	1000hrs	Pass
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	Pass
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	100hrs	Pass
High Temperature Storage	Ta=150degC	1000hrs	Pass
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times	Pass
Solderability	245degC,3s(with Flux) Soldering area,95% over(Sn-3.0Ag-0.5Cu)	1time	Pass

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification. (Except for Solderability)

UPDATE CHANGE NOTIFICATION #20324-D

Package name : VCT28

Test Items	Test Condition	Test Time	Results
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended	1000hrs	Pass
Temperature Humidity Storage *	Ta=85degC,RH=85%	1000hrs	Pass
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	Pass
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	100hrs	Pass
High Temperature Storage	Ta=150degC	1000hrs	Pass
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times	Pass
Solderability	245degC,3s(with Flux) Soldering area,95% over(Sn-3.0Ag-0.5Cu)	1time	Pass

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification. (Except for Solderability)

Package name : FLGA24

Test Items	Test Condition	Test Time	Results
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended	1000hrs	Pass
Temperature Humidity Storage *	Ta=85degC,RH=85%	1000hrs	Pass
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	Pass
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	100hrs	Pass
High Temperature Storage	Ta=150degC	1000hrs	Pass
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times	Pass
Solderability	245degC,3s(with Flux) Soldering area,95% over(Sn-3.0Ag-0.5Cu)	1time	Pass

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification. (Except for Solderability)

Package name : FLGA49

Test Items	Test Condition	Test Time	Results
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended	1000hrs	Pass
Temperature Humidity Storage *	Ta=85degC,RH=85%	1000hrs	Pass
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	Pass
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	100hrs	Pass
High Temperature Storage	Ta=150degC	1000hrs	Pass
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times	Pass
Solderability	245degC,3s(with Flux) Soldering area,95% over(Sn-3.0Ag-0.5Cu)	1time	Pass

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification. (Except for Solderability)

UPDATE CHANGE NOTIFICATION #20324-D

Package name : FLGA68K

Test Items	Test Condition	Test Time	Results
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended	1000hrs	Pass
Temperature Humidity Storage *	Ta=85degC,RH=85%	1000hrs	Pass
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	Pass
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	100hrs	Pass
High Temperature Storage	Ta=150degC	1000hrs	Pass
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times	Pass
Solderability	245degC,3s(with Flux) Soldering area,95% over(Sn-3.0Ag-0.5Cu)	1time	Pass

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification. (Except for Solderability)

ELECTRICAL CHARACTERISTIC SUMMARY:
There is no change in the electrical performance. Datasheet specifications remain unchanged.

CHANGED PART IDENTIFICATION:
Products manufactured at SSMP will be marked with 'L7' preceding the Serial No. on shipping label.

List of affected General Parts:

LB11620GP-H
LB11620GP-TE-L-H
LC709201F01RD-TE-L-H
LC709201F02RD-TE-L-H
LC709202FRD-01-2H
LC709202FRD-01-MH
LC709202FRD-02-2H
LC709202FRD-02-MH
LC717A00AR-NH
LC717A00ARZ-NH
LC717A10AR-NH
LC87FBG08AURE-TE-L-H
LC898113-TBM-H
LC898220A-TE-B-H
LC898221RA-NH
LV5207LP-E
LV5207LP-TE-L-E
LV5217GP-E
LV5217GP-TE-L-E
LV5254LG-MPB-E
LV5254LG-TLM-E
LV5256GP-E
LV5256GP-TE-L-E
LV56081GP-E
LV56081GP-TE-L-E
LV5609LP-E
LV5609LP-TE-L-E
LV5710GP-TE-L-H
LV8075LP-E
LV8075LP-TE-L-E
LV8080LP-E
LV8080LP-TE-L-E
LV8402GP-H
LV8402GP-TE-L-H
LV8411GR-E
LV8411GR-TE-L-E
LV8413GP-E
LV8413GP-H
LV8413GP-TE-L-E
SS30-E
SS30-TE-L-E

List of affected Customer Specific Parts:

LC824112-12H-TBM-H LC87FBG08A5CA1TE-L-H LC87FBG08A5CA9TE-L-H